



Material Content Data Sheet



Sales Product Name		BSC100N06LS3 G		Issued		19. July 2018		
MA#		MA001307572						
Package		PG-TDSON-8-5		Weight*		119.01 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.296	1.09	1.09	10890	10890
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		318	
	inorganic material	phosphorus	7723-14-0	0.011	0.01		95	
	non noble metal	copper	7440-50-8	37.762	31.74	31.78	317302	317715
wire	non noble metal	copper	7440-50-8	0.059	0.05	0.05	495	495
encapsulation	organic material	carbon black	1333-86-4	0.086	0.07		724	
	plastics	epoxy resin	-	6.120	5.14		51427	
	inorganic material	silicondioxide	60676-86-0	36.894	31.00	36.21	310013	362164
leadfinish	non noble metal	tin	7440-31-5	1.452	1.22	1.22	12198	12198
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1391	1391
solder	noble metal	silver	7440-22-4	0.037	0.03		309	
	non noble metal	tin	7440-31-5	0.029	0.02		247	
	non noble metal	lead	7439-92-1	1.404	1.18	1.23	11794	12350
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		95	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		29	
	non noble metal	copper	7440-50-8	11.320	9.51	9.52	95119	95243
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		188	
	inorganic material	phosphorus	7723-14-0	0.007	0.01		56	
	non noble metal	copper	7440-50-8	22.292	18.73	18.76	187310	187554
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com